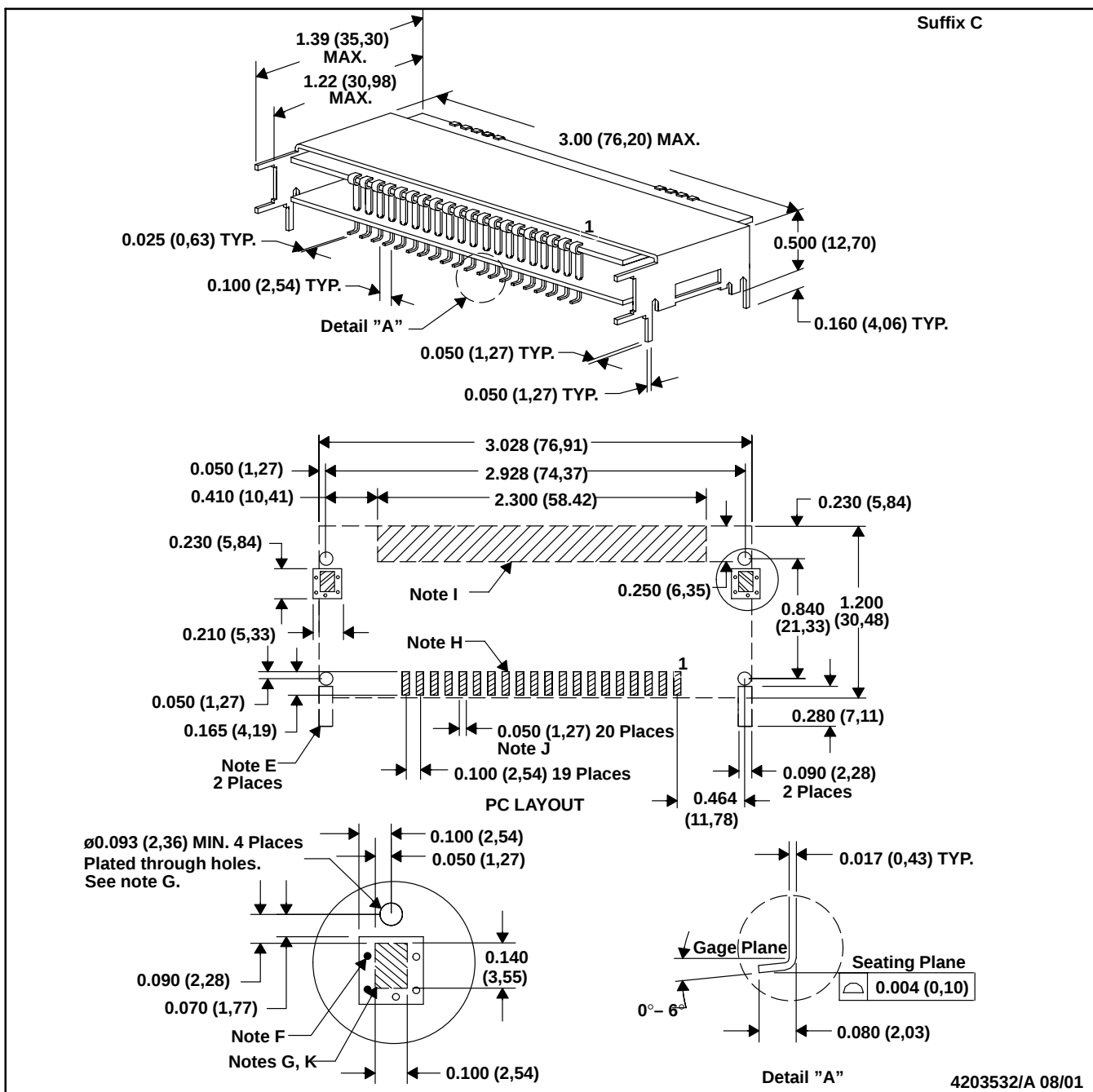


ENL (R-MSIP-G20)

METAL SINGLE-IN-LINE MODULE



- NOTES: A. All linear dimensions are in inches (mm).
B. This drawing is subject to change without notice.
C. 2 place decimals are ± 0.030 (± 0.76 mm).
D. 3 place decimals are ± 0.010 (± 0.25 mm).
E. Recommended mechanical keep out area.
F. Vias are recommended to improve copper adhesion.
G. Solder mask openings to copper island for solder joints to mechanical pins.

- H. Power pin connections should utilize two or more vias per input, ground and output pin.
I. No copper, power or signal traces in this area.
J. Some pins may not be present, see product specifications.
K. The case is electrically uncommitted. The recommended connection is to secondary ground plane.

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